

WN-1439

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semiconductor chips and interconnection layers connecting the chip electrodes and the bump electrodes, wherein the chip electrodes are not located directly across the chip from the bump electrodes."

In the claims:

✓ Please cancel claims 5 and 12-17


REMARKS

Claims 5 and 12-17 have been canceled. Claims 10, 11, and 18-28 were previously allowed, as indicated in the Advisory Action. By this amendment, only claims 10, 11, and 18-28 remain in the application, thus the application is now in *prima facie* condition for allowance.

The amendment to the specification has been made in order to speed prosecution of this case.

Entry of this amendment and allowance of the claims at an early date is requested.

Respectfully submitted,

  
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I certify that this amendment is being filed by the facsimile filing procedure on January 22, 1998, by transmission to the U.S. Patent and Trademark Office at telephone number 308-7722.

